

TP(P12)Mini1II.Gen



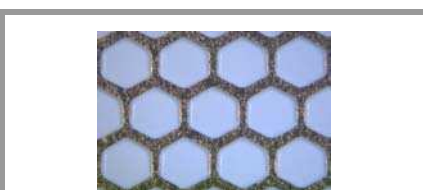
MiniSKiiP®

Pre applied thermal paste
Wacker P12 (silicone based)

TP(P12)Mini1II.Gen

Features

- Honeycomb structure
- Optimized thickness of thermal paste layer
- Enhanced heat dissipation
- High process reliability due to automated screen printing process



honeycomb structure

| Characteristics | | | | | |
|--|----------------------------|------|-------------------|------|--------------------------------------|
| Symbol | Conditions | min. | typ. | max. | Unit |
| Characteristics of printing process | | | | | |
| d_{tp} | thickness of thermal paste | 20 | 30 | 40 | μm |
| Storage conditions | | | | | |
| t_{stg} | storage time | | | 18 | month |
| T_{stg} | storage temperature | -25 | | 60 | $^{\circ}\text{C}$ |
| RH_{stg} | storage humidity | 10 | | 95 | % |
| Characteristics of thermal paste | | | | | |
| γ_{tp} | specific gravity | | 2.25 | | g/cm^3 |
| R_{tp} | resistivity | | $1 \cdot 10^{13}$ | | Ω/cm |
| E_{tp} | dielectric strength | | 20 | | kV/cm |
| λ_{tp} | thermal conductivity | | 0.8 | | $\text{W}/(\text{K} \cdot \text{m})$ |

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our staff.